

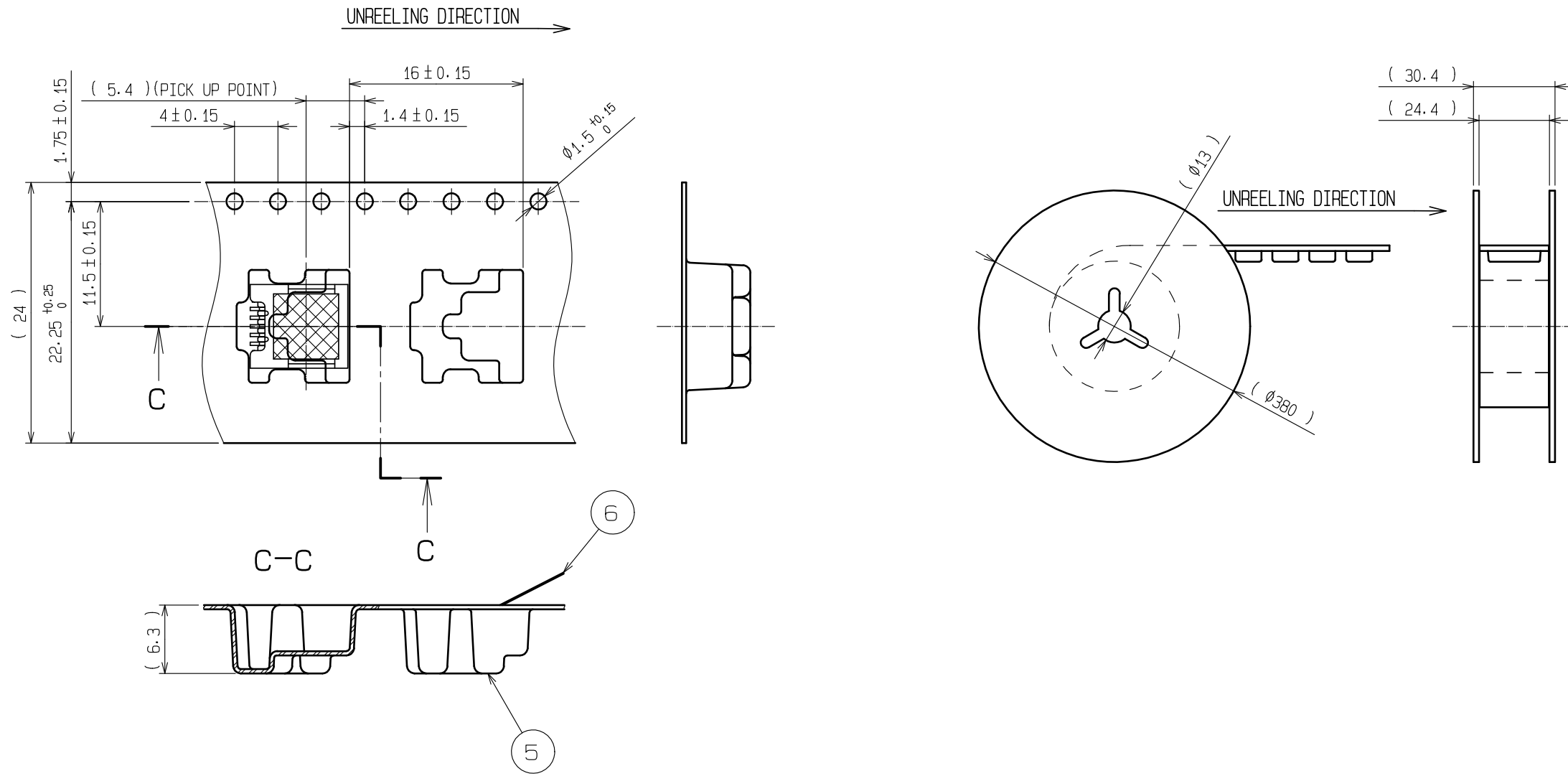
NOTES 1 INTERFACE DIMENSIONS CONFORM TO USB2.0 STANDARDS.
 2 ALL 5 LEADS SMT AND CO-PLANARITY SHALL BE AS FOLLOWS.

SMT AGAINST DATUM Z	CO-PLANARITY
0±0.075	WITHIN 0.1

3 PER REEL:1000 PIECES

3	Copper Alloy	Tin reflow plating			
2	Copper Alloy	Contact area:gold plating 0.75µm min Lead area :tin reflow plating 1µm min Under :nickel plating 1.25µm min	6	PS	
1	LCP	Black UL94V-0	5	PS	
			4	PA	
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS	mm	SCALE	5 : 1	COUNT	1
DESCRIPTION OF REVISIONS			DESIGNED	CHECKED	DATE
DIS-E-00003186			MO. SHIMOYAMA	TU. TANIGUCHI	20200728
APPROVED :MN. KENJO 20200407			DRAWING NO. EDC-123210-70-00		
CHECKED :TU. TANIGUCHI 20200407			PART NO. UX60-MB-5S8(70)		
DESIGNED :KIM JAEHYEON 20200407			CODE NO. CL240-0002-1-70		
DRAWN :DS. HIROWATARI 20200407			1/2		

DRAWING FOR PACKING



HRS	DRAWING NO.	EDC-123210-70-00
	PART NO.	UX60-MB-5S8(70)
	CODE NO.	CL240-0002-1-70
		2/2